

- . One of the best Lm/W, Lm/\$ in Mid-Power LED (高光效、高性价比)
- . Mid-Power EMC packaging LED – 3030 1w Series (LED-3030 1W系列)

T3CYE012C-\*\*AA (PC Amber)



## Product Brief (产品简介)

### Features and Benefits (特性优点)

- . Thermally Enhanced EMC Package Design (高耐热EMC封装)
- . Mid Power to High Power, up to 1.3W (中功率, 最大使用功率 1.3W)
- . Max. Driving Current 400mA (最大操作电流400mA)
- . Pb-free Reflow Soldering Application (适用无铅回流焊)

### Key Applications(应用)

- . Turning Lamp (方向灯)
- . Signal Lamp (讯号灯)

## Table 1. Product Selection Table (产品目录)

Model No. 型号	Color 颜色	WD 波长		
		Min. 最小值	Typ. 典型值	Max. 最大值
T3CYE012C-**AA	PC Amber	585nm	590nm	596nm

## Performance Characteristics (特性参数)

Table 2. Electro Optical Characteristics (光电特性), IF = 350mA, Ta = 25°C, RH60%

WD 波长	Luminous Flux (IF=350mA) 光通量	
	Typ 典型值	Min 最小值
585-595	118	107

- Tolerance of measurements of the Luminous Flux is  $\pm 7\%$  (LM测试误差 $\pm 7\%$ )
- The lumen table is only for reference (LM参数供参考)
- Ta = 25°C, RH60% (温度: 25 °C, 湿度: 60%)

## Performance Characteristics (特性参数)

Table 3. Electro Optical Characteristics (光电特性),  $I_F = 350\text{mA}$ ,  $T_a = 25^\circ\text{C}$ , RH60%

Item 参数	Symbol 符号	Value 数值			Unit 单位	Test Condition 测试条件
		Min 最小值	Typ 典型值	Max 最大值		
Forward Voltage 正向电压	VF	3.0	3.1	3.3	V	$I_F=350\text{mA}$
Reverse Current 反向电流	IR	-	-	10	$\mu\text{A}$	$V_R=5\text{V}$
View Angle 发光角度	$2\theta_{1/2}$	-	120	-	$^\circ$	$I_F=350\text{mA}$
Thermal Resistance 热阻	$(R_{th\ j-sp})$	-	14	-	$^\circ\text{C}/\text{W}$	$I_F=350\text{mA}$
Electrostatic Discharge 抗静电	ESD	8000	-	-	V	-

- Tolerance : VF : $\pm 0.1\text{V}$  (VF测试误差 $\pm 0.1\text{V}$ )
- $2\theta_{1/2}$  is the off-axis where the luminous intensity is 1/2 of the peak intensity ( $2\theta_{1/2}$ 即为发光强度为峰值强度1/2的角度)
- Thermal resistance :  $R_{thJS}$  (Junction / solder) 热阻值 (结点至焊点)
- $T_a = 25^\circ\text{C}$ , RH60% (温度:  $25^\circ\text{C}$ , 湿度: 60%)

## Performance Characteristics (特性参数)

Table 4. Absolute Maximum Ratings (最大额定参数),  $T_a = 25^\circ\text{C}$ , RH60%

Item 参数名称	Symbol 符号	Absolute Maximum Ratings 最大额定参数	Unit 单位
Forward Current 正向电流	IF	400	mA
Pulse Forward Current 正向脉冲电流	IFP	500	mA
Power Dissipation 功率损耗	PD	1360	mW
Reverse Voltage 反向电压	VR	5	V
Operating Temperature 操作温度	Topr	-40~+105	°C
Storage Temperature 储存温度	Tstg	-40~+85	°C
Junction Temperature 结温	Tj	125	°C
Soldering Temperature 回流温度	Tsld	230°C or 260°C for 10sec	

- IFP condition with Pulse: Width $\leq$ 100 $\mu$ s Duty cycle $\leq$ 1/10
- LED's properties might be different from suggested values like above and below tables if operation condition will be exceeded our parameter range. Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product
- 正向脉冲电流条件:脉冲宽度 $\leq$ 100 $\mu$ s, 占空比 $\leq$ 1/10
- 操作条件若超出最大额定参数, 可能会对LED造成不可预期伤害

## Relative Spectral Distribution (光谱分布)

Fig 1. Color Spectrum (光谱图),  $T_a = 25^\circ\text{C}$ , RH60%

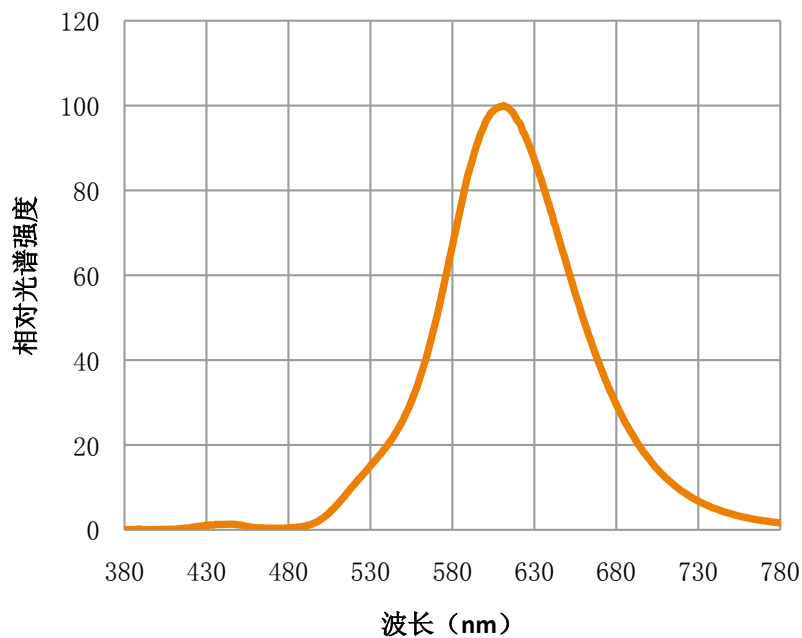
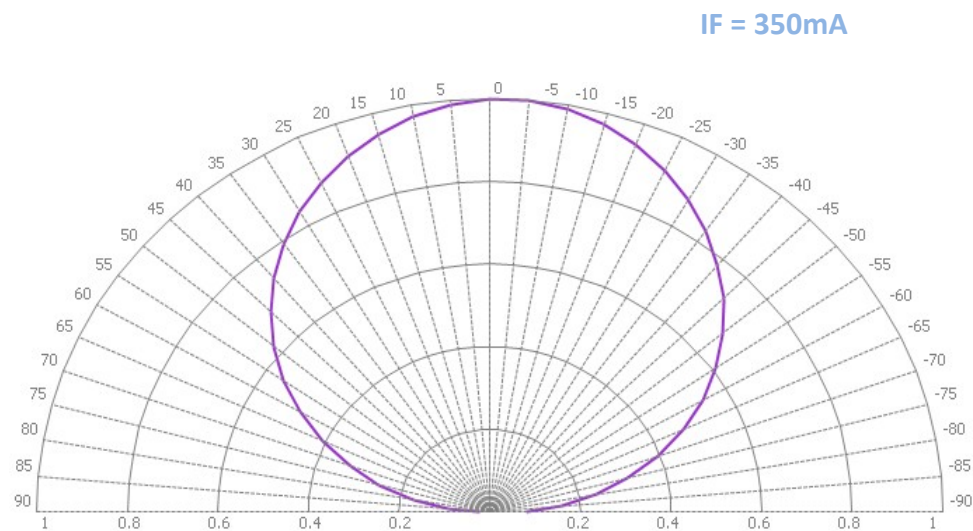


Fig 2. Viewing Angle Distribution (发光角度),  $T_a = 25^\circ\text{C}$ , RH60%



## Forward Current Characteristics (IV特性曲线)

Fig 3. IF--- Relative Luminous flux , Ta = 25°C  
(亮度与电流关系, 温度=25 °C)

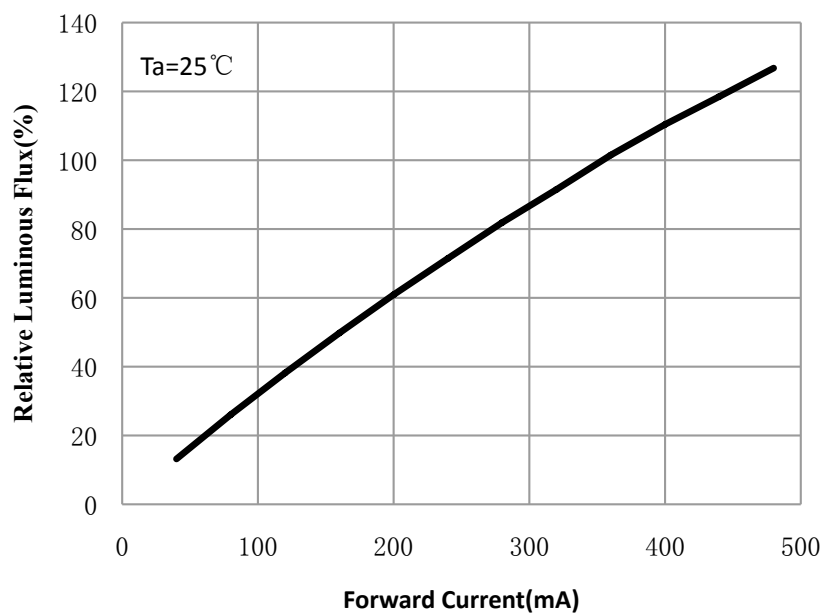
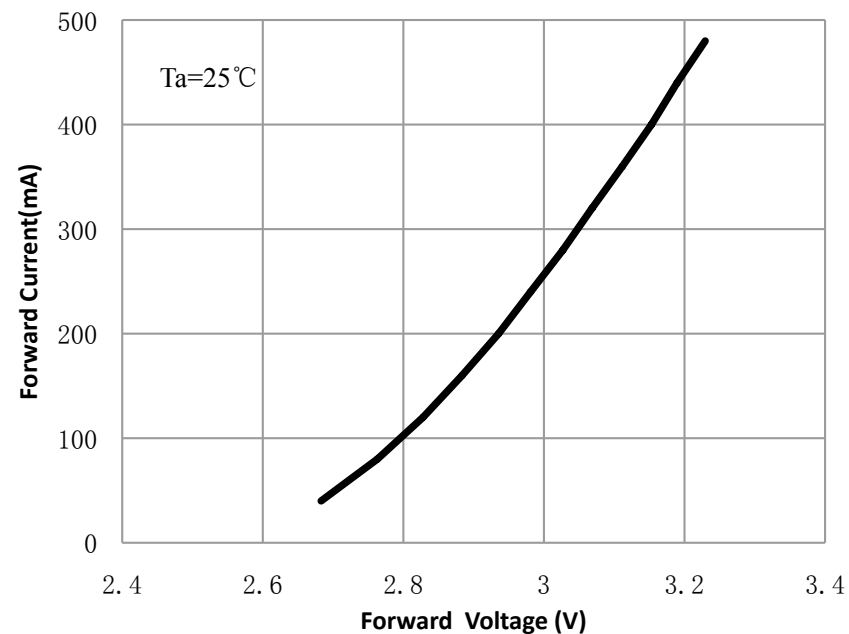
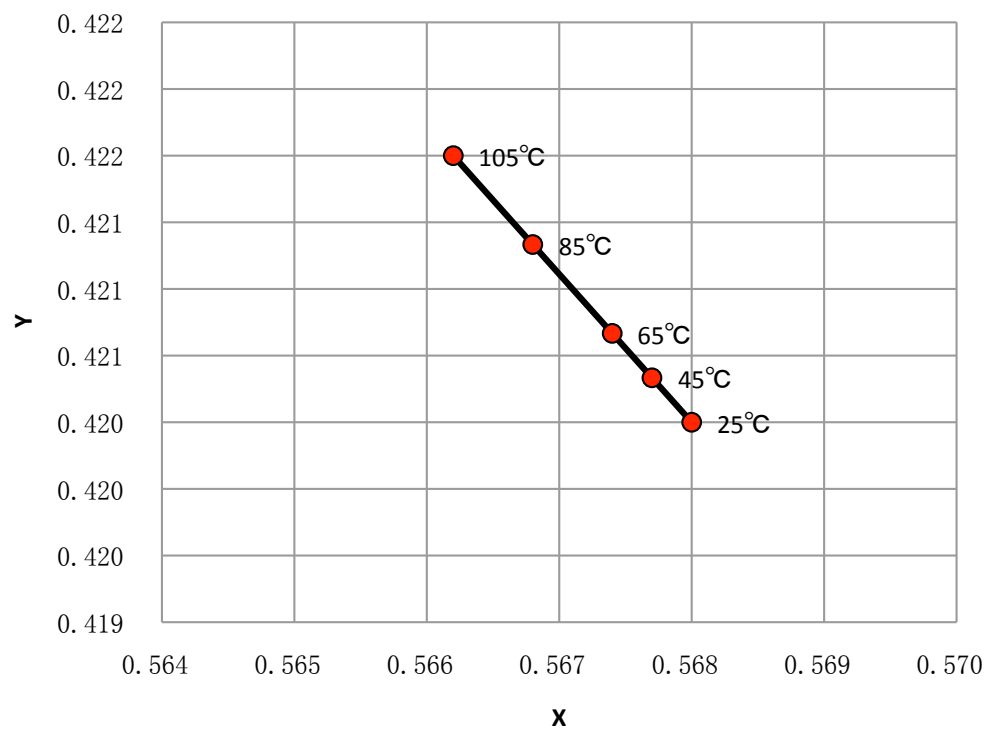


Fig 4. Forward Voltage vs. Forward Current , Ta = 25°C  
(电压与电流关系, 温度=25 °C)



## Ta vs. CIE x, y Shift (温度漂移曲线)

Fig 5. Ta vs. CIE x, y Shift (温度与CIE x, y 关系)



## Iv & Vf VS Temperature Characteristics (亮度与电压 vs 温度)

Fig 6. Ta—Relative Luminous flux (温度与亮度关系)

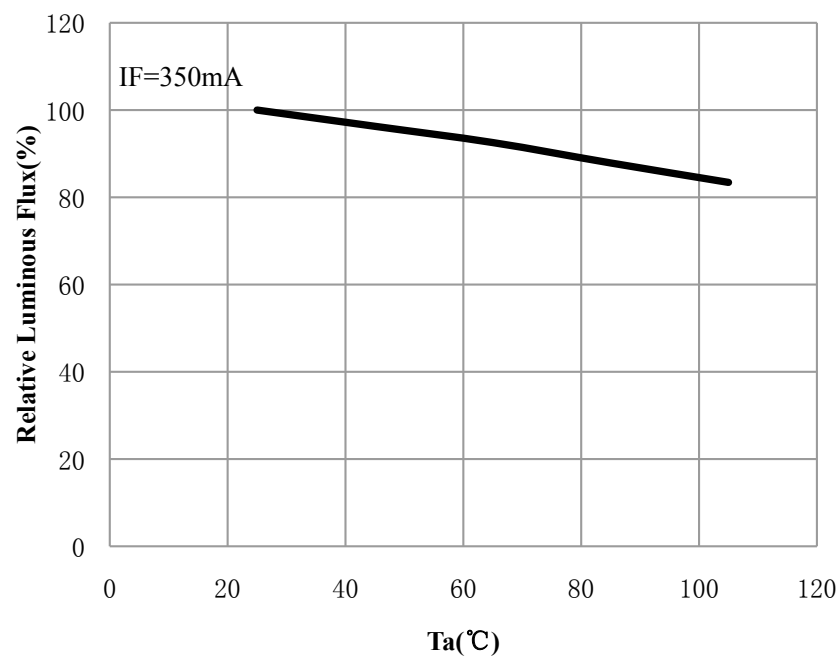
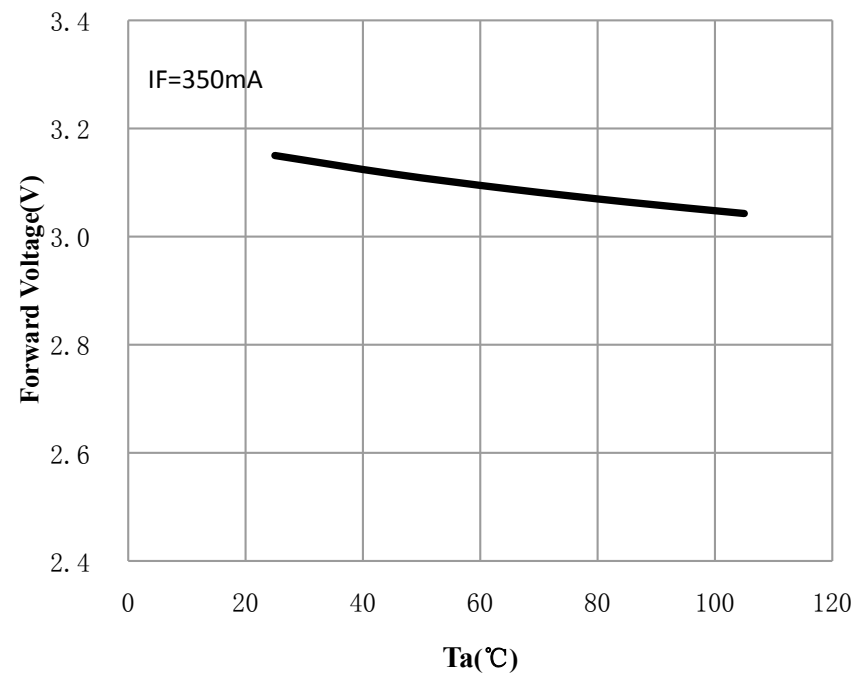


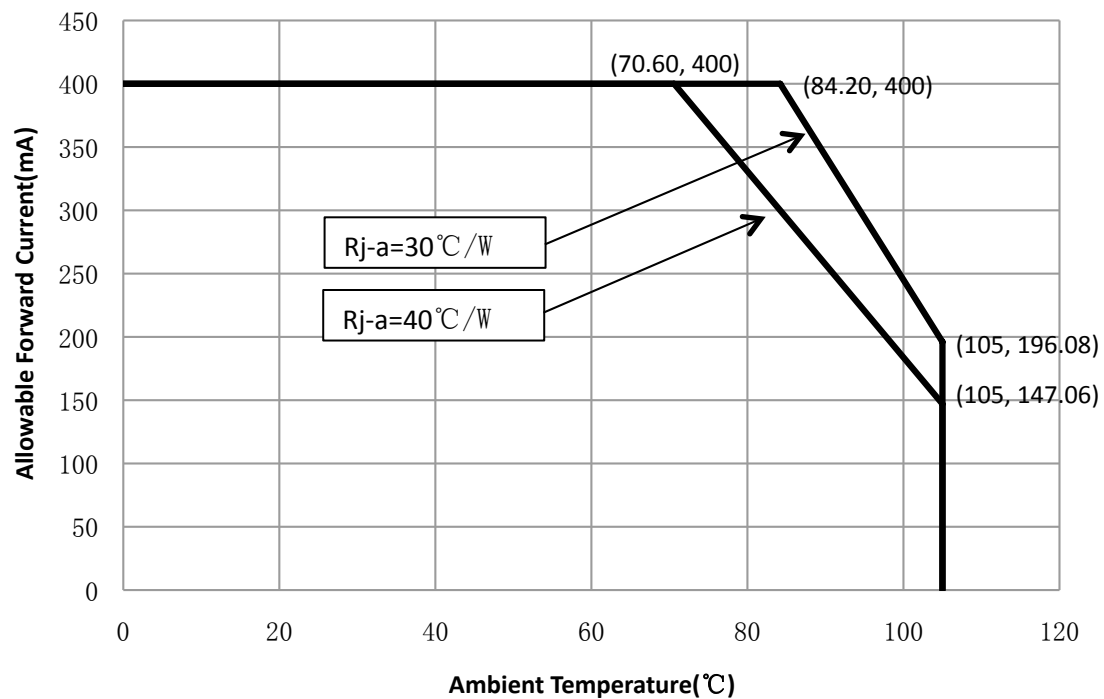
Fig 7. Ta—Forward Voltage (温度与电压关系)





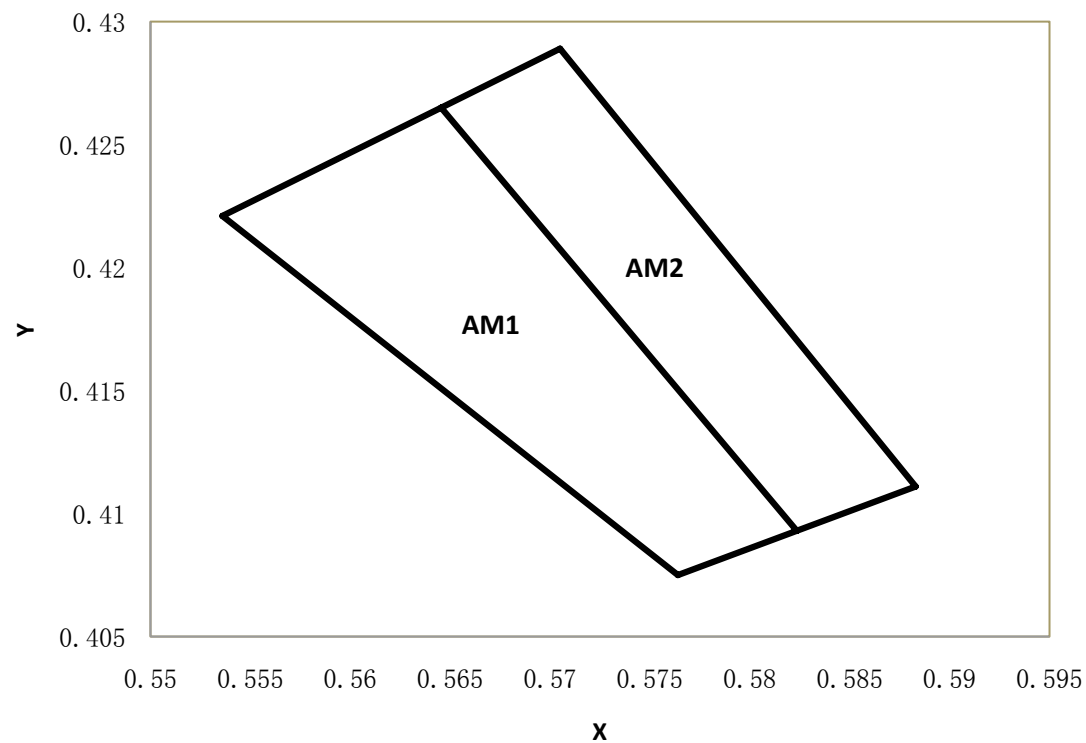
## Ambient Temperature Characteristics (电流温度关系特性)

Fig 8, Maximum Forward Current vs. Ambient Temperature (最大正向电流 vs 环境温度)



## Color Bin Structure (分色方式)

Fig 9, CIE Chromaticity Diagram (CIE色区图),  $I_F = 350\text{mA}$ ,  $T_a = 25^\circ\text{C}$



- All measurements were made under the standardized environment of Lightning LED.
- 所有测量都在天电标准环境下进行.

## Color Bin Structure (分色方式)

Table 5. Bin Code description (分光色区图), IF = 350mA, Ta = 25°C, RH60%

Colour Bin 色区	X	Y
AM1	0.5536	0.4221
	0.5764	0.4075
	0.58235	0.4093
	0.56455	0.4265
AM2	0.56455	0.4265
	0.5705	0.4289
	0.5883	0.4111
	0.58235	0.4093

- Measurement Uncertainty of the Color Coordinates :  $\pm 0.007$  (色坐标的测试误差:  $\pm 0.007$ )
- Ta = 25°C, RH60% (温度: 25°C, 湿度: 60%)

## Luminous Flux Bin Structure (分光方式)

Table 6. Luminous Flux Ranks (光通量分档), IF = 350mA, Ta = 25°C, RH60%

Color Bin 色区	Luminous Flux 光通量 (IF=350mA)		
	Code 代码	Min 最小值	Max 最大值
AM1 & AM2	2C	107	114
	2D	114	122
	2E	122	130

- Tolerance of measurements of the Luminous Flux is  $\pm 7\%$  (光通量的测量误差:  $\pm 7\%$ )
- Ta = 25°C, RH60% (温度: 25 °C, 湿度: 60%)

## Forward Voltage Bin Structure (分压方式)

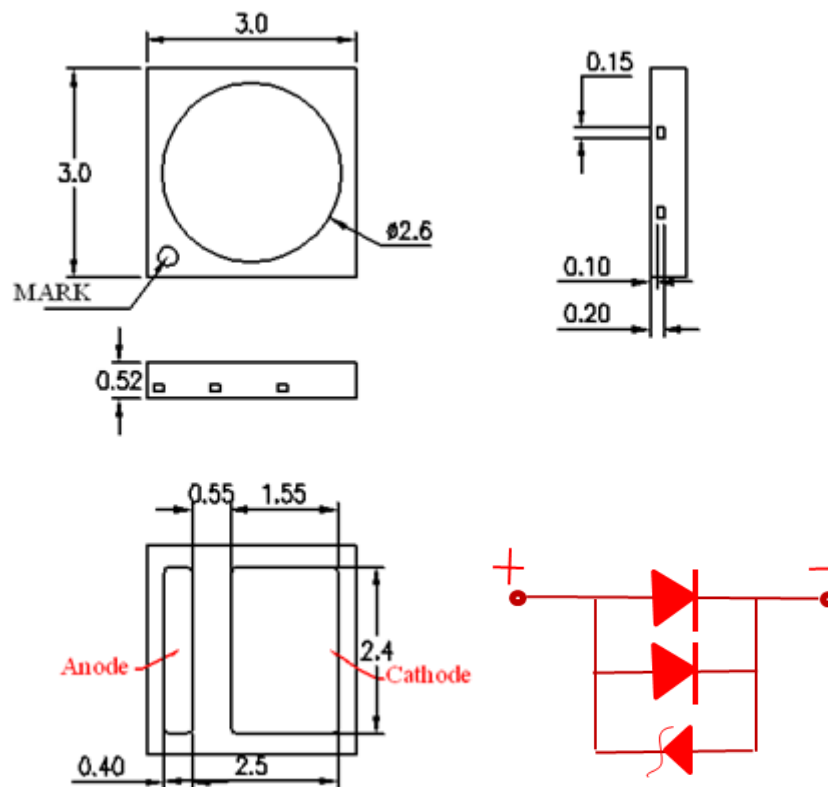
Table 7. Forward Voltage Ranks (正向电压分档) ,  $I_F = 350\text{mA}$  ,  $T_a = 25^\circ\text{C}$  , RH60%

Code 代码	Min 最小值	Max 最大值	Unit 单位
G	3.0	3.1	V
H	3.1	3.2	V
I	3.2	3.3	V

- Tolerance of measurements of the Forward Voltage is  $\pm 0.1\text{V}$  (正向电压的测量误差:  $\pm 0.1\text{V}$ )
- $T_a = 25^\circ\text{C}$  , RH60% (温度:  $25^\circ\text{C}$  , 湿度: 60%)

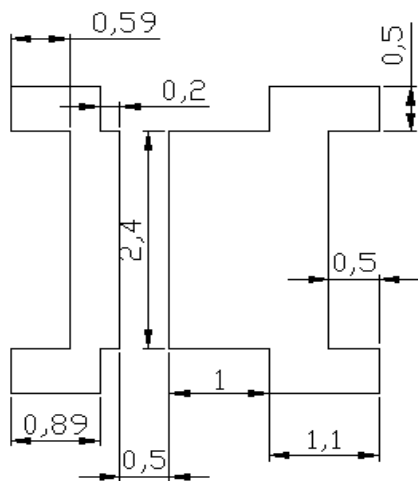
## Mechanical Dimensions (产品尺寸)

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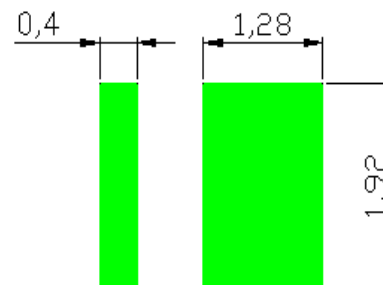


- All dimensions are in millimeters (图中所有尺寸均以毫米为单位)
- Scale : 1:1 (比例: 1:1)
- Undefined tolerance is  $\pm 0.2$ mm (尺寸公差:  $\pm 0.2$ 毫米)

## Recommended Solder Pad (焊盘设计)



Recommended solder pad  
建议焊盘

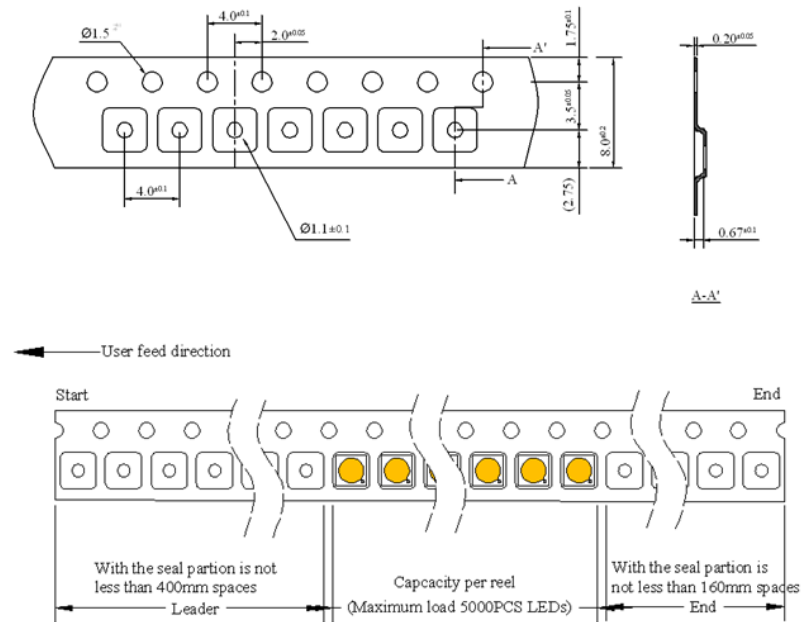


Recommended stencil opening  
建议钢网

- All dimensions are in millimeters
- Scale : 1:1
- This drawing without tolerances are for reference only
- Undefined tolerance:  $\pm 0.10\text{mm}$
- 图中所有尺寸均以毫米为单位
- 比例: 1:1
- 图纸仅供参考
- 若无特殊标注, 图中公差尺寸为 $\pm 0.10\text{mm}$

## Packaging Information (包装信息)

### Reel Packaging (卷带包装)

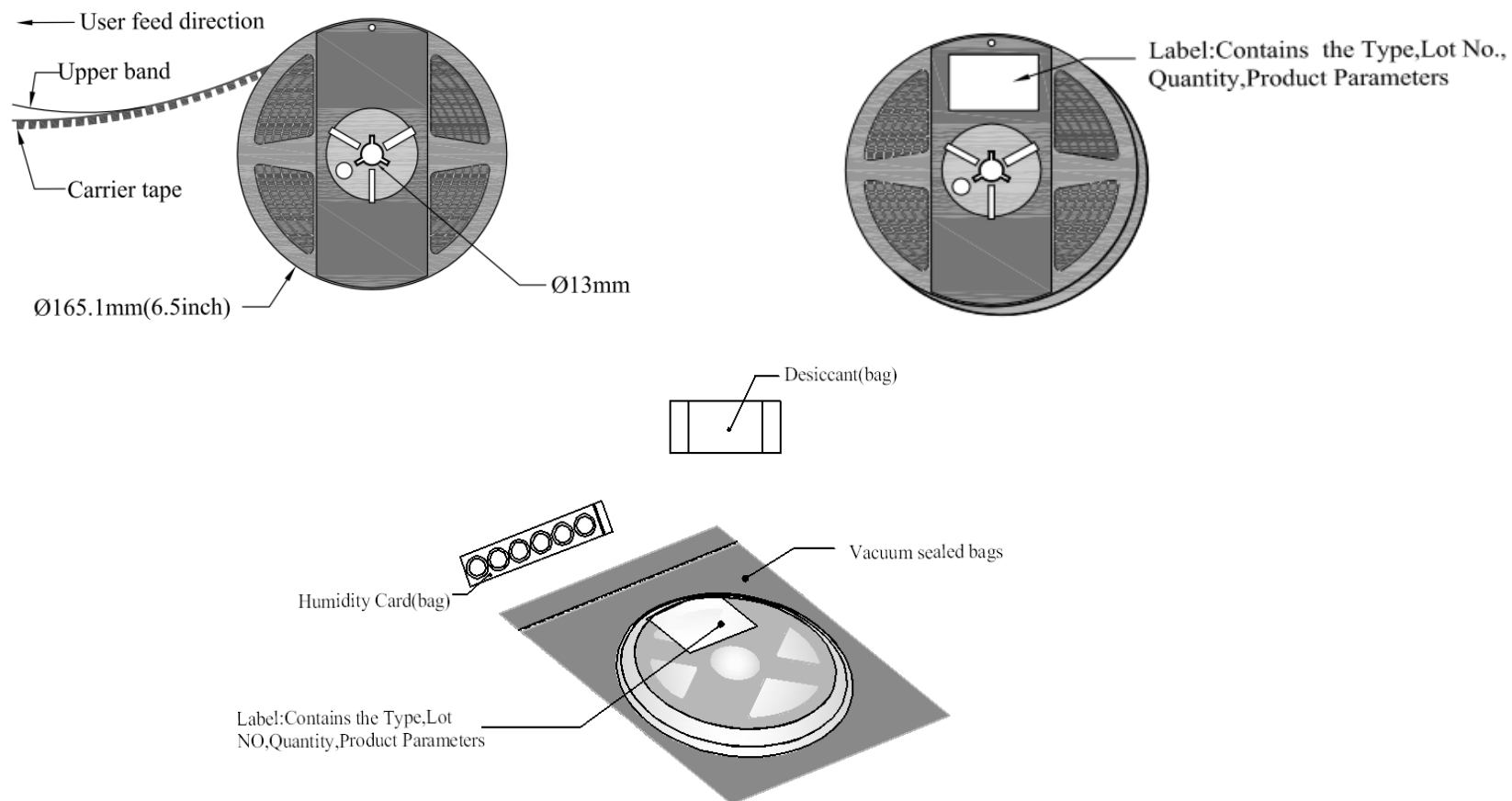


- Quantity : Max 5000pcs/Reel
- Cumulative Tolerance : Cumulative Tolerance/10 pitches to be  $\pm 0.2\text{mm}$
- Adhesion Strength of Cover Tape Adhesion strength to be 0.1-0.7N when the cover tape is turned off from the carrier tape at the angle of  $10^\circ$  to the carrier tape.
- Package : P/N, Manufacturing data Code No. and Quantity to be indicated on a damp proof Package
- 数量: 最多5000pcs/卷
- 10 pitches累积公差 : $\pm 0.2\text{mm}$
- 上带剥离强度为0.1-0.7N (上带与载带成 $10^\circ$ 角剥离)
- 包装信息包含料号, 生产日期及数量等



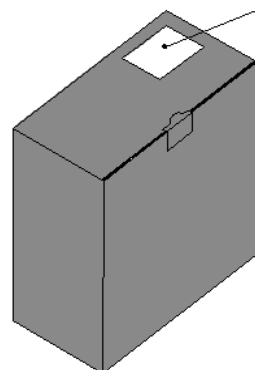
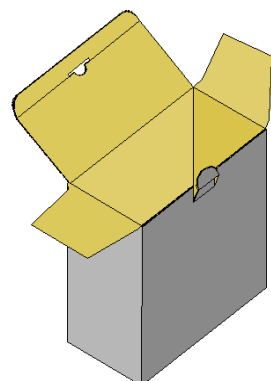
## Packaging Information (包装信息)

### Reel Packaging (卷带包装)



## Packaging Information (包装信息)

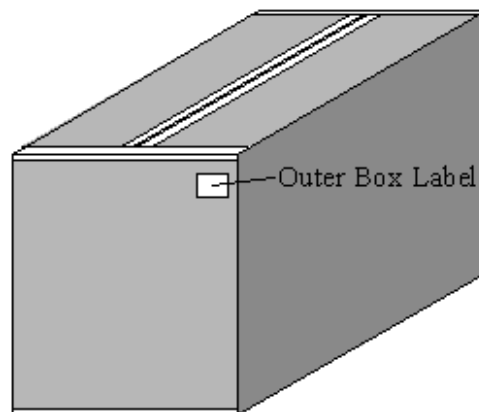
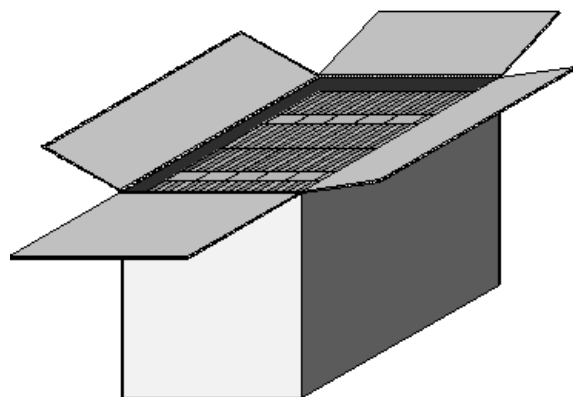
### Inner Box (内箱)



Label: Contains Type,  
Lot NO, Quantity, Product  
Parameters.



\* Capacity 5 or 10 reels per box (内箱容量: 5或10卷)

### Outer Box (外箱)



Outer Box Label

### Label (标签)

Type:	T3CYE012C-**AA	
<u>Vf@350mA</u>	-	[V] 
<u>Φ@350mA</u>	-	[Lm]
Color Bin	-	-
<u>Ra@350mA</u>		Date:
Lot No.: XXXXXX-XX		QTY: 5000PCS

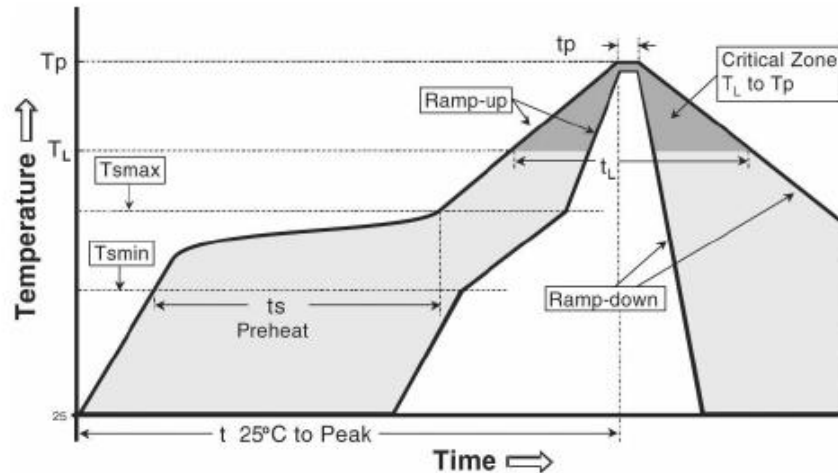
\* Capacity 30 or 60 reels per box (外箱容量: 30或60卷)

## Product Nomenclature (命名原则)

Table 8. Part Numbering System (命名原则) : T  $\square\square$   $\square\square$   $\square$   $\square$   $\square$   $\square$  -  $\square\square$   $\square\square$   
X1 X2 X3 X4 X5 X6 X7 X8

Item Number Code 序号代码	Description 描述	Content 内容
X1	Type code 产品代码	34:3020; 3A:K285; 3B:3014; 3C:3030; 5A:5050N; 32: 3528; 19: Ceramic 3535; 15: Ceramic 5050; 12: Ceramic 9292; 20: 2016.
X2	Colour code 颜色代码	BL:Blue ; RE:Red ;GR:Green ;YE:Yellow(PC Amber)
X3	Color Rendering 显指	Ra70: 7; Ra80: 8; Ra90: 9
X4	No. of serial chip 晶片串联数量	1-Z.
X5	No. of parallel chip 晶片并联数量	1-Z.
X6	Component code 补充码	A-Z.
X7	Internal code1 内部码1	\
X8	Internal code2 内部码2	\

## Reflow Soldering Characteristics (建议回流焊方式)



Reflow soldering	
Temperature Min ( $T_{smin}$ ) Temperature Max ( $T_{smax}$ ) Time( $t_s$ )from ( $T_{smin}$ to $T_{smax}$ )	150°C 200°C 60-120 seconds.
Ramp-up rate ( $T_L$ to $T_p$ )	3°C/seconds max.
Liquidous temperature( $T_L$ ) Time( $t_L$ ) maintained above $T_L$	217°C 60-150 seconds
Peak package body temperature( $T_p$ )	260°C max
Time ( $t_p$ ) within 5°C of the specified classification temperature( $T_c$ ).	30 seconds max
Ramp-down rate ( $T_p$ to $T_L$ )	6°C/second max
Time 25°C to peak temperature	8 min max

## Pre-caution for use (注意事项)

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### Caution

1. Reflow soldering is recommended not to be done more than two times. In the case of more than 24 hours passed soldering after first, LEDs will be damaged.
2. Repairs should not be done after the LEDs have been soldered. When repair is unavoidable, suitable tools must be used.
3. Die slug is to be soldered.
4. When soldering, do not put stress on the LEDs during heating.
5. After soldering, do not warp the circuit board.

### Notes on Lightning EMC Series soldering:

1. Recommend to use reflow machine.
2. Recommend to use heating plate soldering.
3. Manual soldering is not recommended.

### Notes on reflow process:

1. To confirm whether the actual temperature curve in the reflow soldering conditions comply with recommended conditions. LEDs are guaranteed for one time reflow.
2. During reflow process do not apply force on LED active area.
3. After reflow process, PCB board should be cooled down before packing or storage.

## Pre-caution for use (注意事项)

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### 注意:

1. 回流焊建议不要超过两次。
2. LED焊接后不建议重工，当重工不可避免时,必须使用合适的工具。
3. 不可虚焊。
4. 焊接加热过程中，请勿施加压力于LED表面。
5. 焊接后,请勿弯曲电路板。

### 焊接注意事项:

1. 建议使用回流焊机器。
2. 建议使用加热板焊接。
3. 不建议手动焊接。

### 回流焊注意事项:

1. 确保实际温度曲线与回流焊接条件相符合。
2. 在回流过程中，请勿施加压力于LED表面。
3. 回流后，PCB板在包装或存储前需冷却至常温。

Revision record 修订记录				
DOC.NO 文件编号	Version 版本	Page 页数	Content of change 变更内容	Date 日期
SZTDPSA-3C-37	A00	23	/	2015/7/3
SZTDPSA-3C-37	A01	23	VF 分档方式变更	2015/11/16
SZTDPSA-3C-37	A02	3	VF 变更	2015/11/17